

METHOD OF PROCESSING WAFER

ABSTRACT OF THE DISCLOSURE

A method of processing a wafer includes a protective member affixing step of affixing a protective member whose area covers a face side or a reverse side of the wafer to the wafer, and after the protective member affixing step has been carried out, a ring-shaped stiffener removing step of removing a ring-shaped stiffener from the wafer. The ring-shaped stiffener removing step includes a ring-shaped stiffener separating step of dividing the wafer along an outer circumference of a device region to separate the device region and the ring-shaped stiffener from each other, and after the ring-shaped stiffener separating step has been carried out, a removing step of processing the ring-shaped stiffener with a grindstone to remove the ring-shaped stiffener from the wafer while a processing fluid is being supplied to the wafer.

[Fig. 4]